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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

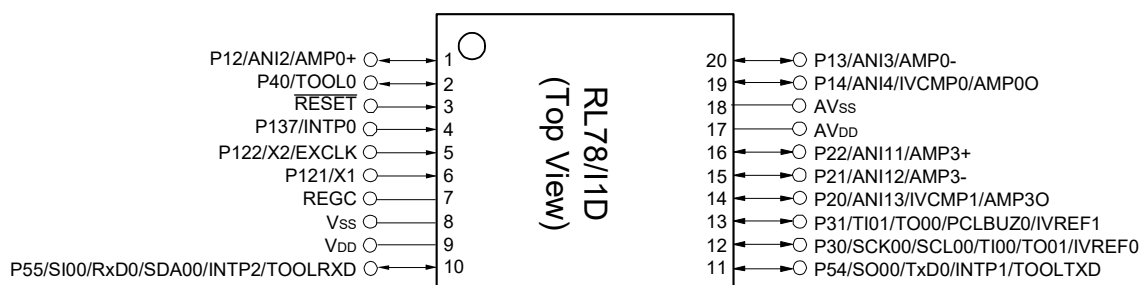
Details

Product Status	Active
Core Processor	RL78
Core Size	16-Bit
Speed	24MHz
Connectivity	CSI, I ² C, UART/USART
Peripherals	LVD, POR, WDT
Number of I/O	11
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 3.6V
Data Converters	A/D 6x8/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	20-LSSOP (0.173", 4.40mm Width)
Supplier Device Package	20-LSSOP
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f1176agsp-30

1.3 Pin Configuration (Top View)

1.3.1 20-pin products

<R> • 20-pin plastic LSSOP (4.4 × 6.5 mm, 0.65 mm pitch)



Caution 1. Connect the REGC pin to Vss pin via a capacitor (0.47 to 1 μ F).

Caution 2. Make AVss pin the same potential as Vss pin.

Caution 3. Make AVDD pin the same potential as VDD pin.

Remark For pin identification, see 1.4 Pin Identification.

1.4 Pin Identification

ANI0 to ANI13,	: Analog input	PCLBUZ0, PCLBUZ1	: Programmable clock output/buzzer output
ANI16 to ANI18			
AVDD	: Analog power supply	REGC	: Regulator capacitance
AVREFM	: A/D converter reference potential (- side) input	$\overline{\text{RESET}}$	: Reset
AVREFP	: A/D converter reference potential (+ side) input	RTC1HZ	: Real-time clock correction clock (1 Hz) output
AVss	: Analog ground	RxD0	: Receive data
EXCLK	: External clock input (main system clock)	SCK00, SCK01	: Serial clock input/output
EXCLKS	: External clock input (subsystem clock)	SCL00, SCL01	: Serial clock input/output
INTP0 to INTP6	: External interrupt input	SDA00, SDA01	: Serial data input/output
IVCMP0, IVCMP1	: Comparator input	SI00, SI01	: Serial data input
IVREF0, IVREF1	: Comparator reference input	SO00, SO01	: Serial data output
KR0 to KR3	: Key return	$\overline{\text{SSI00}}$	: Serial interface chip select input
P00 to P04	: Port 0	TI00 to TI03	: Timer input
P10 to P17	: Port 1	TO00 to TO03	: Timer output
P20 to P25	: Port 2	TOOL0	: Data input/output for tool
P30 to P33	: Port 3	TOOLRXD, TOOLTXD	: Data input/output for external device
P40	: Port 4	TxD0	: Transmit data
P50 to P57	: Port 5	VCOU0, VCOU1	: Comparator output
P60 to P63	: Port 6	AMP0+, AMP1+,	: Operational amplifier (+side) input
P121 to P124	: Port 12	AMP2+, AMP3+	
P130, P137	: Port 13	AMP0-, AMP1-,	: Operational amplifier (-side) input
		AMP2-, AMP3-	
		AMP0O, AMP1O,	: Operational amplifier output
		AMP2O, AMP3O	
		VDD	: Power supply
		Vss	: Ground
		X1, X2	: Crystal oscillator (main system clock)
		XT1, XT2	: Crystal oscillator (subsystem clock)

2.3 DC Characteristics

2.3.1 Pin characteristics

($T_A = -40$ to $+85^\circ\text{C}$, $1.6\text{ V} \leq AV_{DD} = V_{DD} \leq 3.6\text{ V}$, $V_{SS} = AV_{SS} = 0\text{ V}$)

($T_A = +85$ to $+105^\circ\text{C}$, $2.4\text{ V} \leq AV_{DD} = V_{DD} \leq 3.6\text{ V}$, $V_{SS} = AV_{SS} = 0\text{ V}$)

(1/5)

Items	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output current, high Note 1	IOH1	Per pin for P00 to P04, P30 to P33, P40, P50 to P57, P130	$T_A = -40$ to $+85^\circ\text{C}$		-10.0 Note 2	mA
			$T_A = +85$ to $+105^\circ\text{C}$		-3.0 Note 2	mA
		Total of P00 to P04, P40, P130 (When duty $\leq 70\%$ Note 3)	$2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$		-10.0	mA
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$		-5.0	mA
			$1.6\text{ V} \leq V_{DD} < 1.8\text{ V}$		-2.5	mA
		Total of P30 to P33, P50 to P57 (When duty $\leq 70\%$ Note 3)	$2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$		-19.0	mA
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$		-10.0	mA
			$1.6\text{ V} \leq V_{DD} < 1.8\text{ V}$		-5.0	mA
		Total of all pins (When duty $\leq 70\%$ Note 3)			-29.0	mA
	IOH2	Per pin for P10 to P17, P20 to P25			-0.1 Note 2	mA
		Total of all pins (When duty $\leq 70\%$ Note 3)	$1.6\text{ V} \leq V_{DD} \leq 3.6\text{ V}$		-1.4	mA

Note 1. Value of current at which the device operation is guaranteed even if the current flows from the V_{DD} pin to an output pin.

Note 2. Do not exceed the total current value.

Note 3. Specification under conditions where the duty factor $\leq 70\%$.

The output current value that has changed to the duty factor $> 70\%$ the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

- Total output current of pins = $(I_{OH} \times 0.7)/(n \times 0.01)$

<Example> Where $n = 80\%$ and $I_{OH} = -10.0\text{ mA}$

$$\text{Total output current of pins} = (-10.0 \times 0.7)/(80 \times 0.01) \approx -8.7\text{ mA}$$

However, the current that is allowed to flow into one pin does not vary depending on the duty factor.

A current higher than the absolute maximum rating must not flow into one pin.

Caution P30 and P51 to P56 do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

<R>

- Note 1.** Total current flowing into VDD, including the input leakage current flowing when the level of the input pin is fixed to VDD or Vss. The MAX values include the peripheral operating current. However, these values do not include the current flowing into the A/D converter, operational amplifier, comparator, LVD circuit, I/O ports, and on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.
- Note 2.** When the HALT instruction is executed in the flash memory.
- Note 3.** When the high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.
- Note 4.** When the high-speed system clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.
- Note 5.** When the high-speed system clock, middle-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and high-speed on-chip oscillator clock are stopped. When RTCLPC = 1 and ultra-low-power consumption oscillation is set (AMPHS1, AMPHS0) = (1, 0). The values include the current flowing into the real-time clock. However, the values do not include the current flowing into the 12-bit interval timer and watchdog timer.
- Note 6.** When the high-speed on-chip oscillator clock, middle-speed on-chip oscillator clock, high-speed system clock, and sub clock are stopped.
- Note 7.** When the high-speed system clock, high-speed on-chip oscillator clock, low-speed on-chip oscillator clock, and sub clock are stopped.

Remark 1. fMX: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

Remark 2. fIH: High-speed on-chip oscillator clock frequency (24 MHz max.)

Remark 3. fIM: Middle-speed on-chip oscillator clock frequency (4 MHz max.)

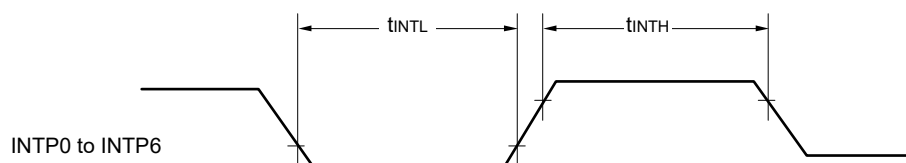
Remark 4. fIL: Low-speed on-chip oscillator clock frequency

Remark 5. fSX: Sub clock frequency (XT1 clock oscillation frequency)

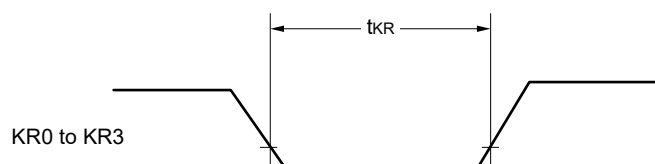
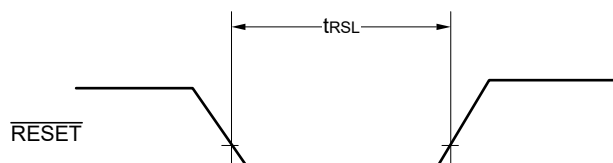
Remark 6. fSUB: Subsystem clock frequency (XT1 clock oscillation frequency or low-speed on-chip oscillator clock frequency)

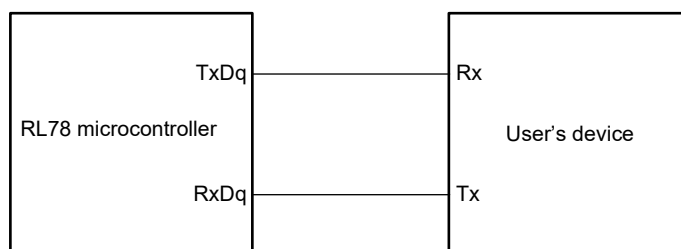
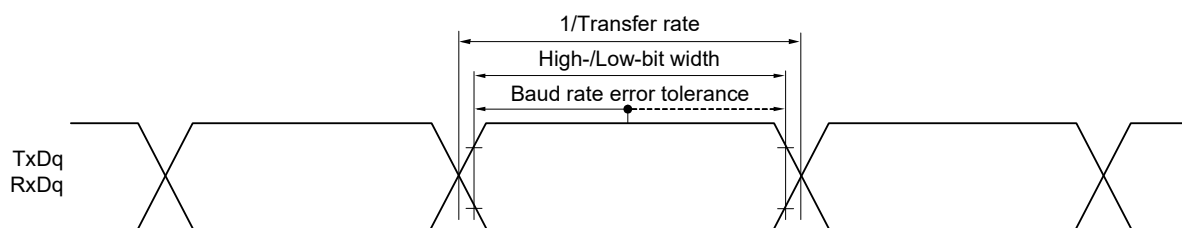
Remark 7. Except subsystem clock operation, temperature condition of the TYP. value is TA = 25°C

Interrupt Request Input Timing



Key Interrupt Input Timing

 $\overline{\text{RESET}}$ Input Timing

UART mode connection diagram (during communication at same potential)**UART mode bit width (during communication at same potential) (reference)**

Remark 1. q: UART number (q = 0), g: PIM and POM number (g = 5)

Remark 2. f_{MCK}: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00, 01))

(3) During communication at same potential (CSI mode) (master mode, SCKp... internal clock output)

(TA = -40 to +85°C, 1.6 V ≤ AVDD = VDD ≤ 3.6 V, VSS = AVSS = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LP (Low-power main) mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time	t _{KCY1}	t _{KCY1} ≥ f _{CLK} /4	2.7 V ≤ V _{DD} ≤ 3.6 V	167		500		4000		1000		ns
			2.4 V ≤ V _{DD} ≤ 3.6 V	250								
			1.8 V ≤ V _{DD} ≤ 3.6 V	—								
			1.7 V ≤ V _{DD} ≤ 3.6 V	—		—		—				
			1.6 V ≤ V _{DD} ≤ 3.6 V	—		—		—				
SCKp high-/low-level width	t _{KH1} , t _{KL1}	2.7 V ≤ V _{DD} ≤ 3.6 V		t _{KCY1} /2 - 18		t _{KCY1} /2 - 50		t _{KCY1} /2 - 50		t _{KCY1} /2 - 50		ns
		2.4 V ≤ V _{DD} ≤ 3.6 V		t _{KCY1} /2 - 38								
		1.8 V ≤ V _{DD} ≤ 3.6 V		—								
		1.7 V ≤ V _{DD} ≤ 3.6 V		—		—		—		t _{KCY1} /2 - 100		
		1.6 V ≤ V _{DD} ≤ 3.6 V		—		—		—				
Slp setup time (to SCKp↑) Note 1	t _{SIK1}	2.7 V ≤ V _{DD} ≤ 3.6 V		58		110		110		110		ns
		2.4 V ≤ V _{DD} ≤ 3.6 V		75								
		1.8 V ≤ V _{DD} ≤ 3.6 V		—								
		1.7 V ≤ V _{DD} ≤ 3.6 V		—		—		—		220		
		1.6 V ≤ V _{DD} ≤ 3.6 V		—		—		—				
Slp hold time (from SCKp↑) Note 2	t _{KS1}	2.4 V ≤ V _{DD} ≤ 3.6 V		19		19		19		19		ns
		1.8 V ≤ V _{DD} ≤ 3.6 V		—								
		1.6 V ≤ V _{DD} ≤ 3.6 V		—		—		—				
Delay time from SCKp↓ to SOp output Note 3	t _{KSO1}	C = 30 pF Note 4	2.4 V ≤ V _{DD} ≤ 3.6 V		33.4		33.4		33.4		33.4	ns
			1.8 V ≤ V _{DD} ≤ 3.6 V		—							
			1.6 V ≤ V _{DD} ≤ 3.6 V		—		—		—			

Note 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 4. C is the load capacitance of the SCKp and SOp output lines.

Caution Select the normal input buffer for the Slp pin and the normal output mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

Remark 1. p: CSI number (p = 00), m: Unit number (m = 0), n: Channel number (n = 0), g: PIM and POM numbers (g = 5)

Remark 2. f_{MCK}: Serial array unit operation clock frequency

(Operation clock to be set by the CKS_{mn} bit of serial mode register mn (SMR_{mn}). m: Unit number, n: Channel number (mn = 00, 01))

(4) During communication at same potential (CSI mode) (slave mode, SCKp... external clock input)

(TA = -40 to +85°C, 1.6 V ≤ AVDD = VDD ≤ 3.6 V, VSS = AVSS = 0 V)

(1/2)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LP (Low-power main) mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time Note 5	tkcy2	2.7 V ≤ VDD ≤ 3.6 V	fMCK > 16 MHz	8/fMCK	—	—	—	—	—	—	—	ns
			fMCK ≤ 16 MHz	6/fMCK	—	6/fMCK	—	6/fMCK	—	6/fMCK	—	
		2.4 V ≤ VDD ≤ 3.6 V		6/fMCK and 500	—	6/fMCK	—	6/fMCK	—	6/fMCK	—	
		1.8 V ≤ VDD ≤ 3.6 V		—	—	6/fMCK	—	6/fMCK	—	6/fMCK	—	
		1.7 V ≤ VDD ≤ 3.6 V		—	—	—	—	—	—	—	—	
		1.6 V ≤ VDD ≤ 3.6 V		—	—	—	—	—	—	—	—	
SCKp high-/low-level width	tkH2, tkL2	2.7 V ≤ VDD ≤ 3.6 V		tkcy2/2 - 8	—	tkcy2/2 - 8	—	tkcy2/2 - 8	—	tkcy2/2 - 8	—	ns
		2.4 V ≤ VDD ≤ 3.6 V		tkcy2/2 - 18	—	tkcy2/2 - 18	—	tkcy2/2 - 18	—	tkcy2/2 - 18	—	
		1.8 V ≤ VDD ≤ 3.6 V		—	—	—	—	—	—	—	—	
		1.7 V ≤ VDD ≤ 3.6 V		—	—	—	—	—	—	tkcy2/2 - 66	—	
		1.6 V ≤ VDD ≤ 3.6 V		—	—	—	—	—	—	—	—	
Slp setup time (to SCKp↑) Note 1	tsik2	2.7 V ≤ VDD ≤ 3.6 V		1/fMCK + 20	—	1/fMCK + 30	—	1/fMCK + 30	—	1/fMCK + 30	—	ns
		2.4 V ≤ VDD ≤ 3.6 V		1/fMCK + 30	—	—	—	—	—	—	—	
		1.8 V ≤ VDD ≤ 3.6 V		—	—	—	—	—	—	—	—	
		1.7 V ≤ VDD ≤ 3.6 V		—	—	—	—	—	—	1/fMCK + 40	—	
		1.6 V ≤ VDD ≤ 3.6 V		—	—	—	—	—	—	—	—	
Slp hold time (from SCKp↑) Note 2	tksi2	2.4 V ≤ VDD ≤ 3.6 V		1/fMCK + 31	—	1/fMCK + 31	—	1/fMCK + 31	—	1/fMCK + 31	—	ns
		1.8 V ≤ VDD ≤ 3.6 V		—	—	—	—	—	—	—	—	
		1.7 V ≤ VDD ≤ 3.6 V		—	—	—	—	—	—	1/fMCK + 250	—	
		1.6 V ≤ VDD ≤ 3.6 V		—	—	—	—	—	—	—	—	
Delay time from SCKp↓ to SOp output Note 3	tkso2	C = 30 pF Note 4	2.7 V ≤ VDD ≤ 3.6 V	—	2/fMCK + 44	—	2/fMCK + 110	—	2/fMCK + 110	—	2/fMCK + 110	ns
			2.4 V ≤ VDD ≤ 3.6 V	—	2/fMCK + 75	—	—	—	—	—	—	
			1.8 V ≤ VDD ≤ 3.6 V	—	—	—	—	—	—	—	—	
			1.7 V ≤ VDD ≤ 3.6 V	—	—	—	—	—	—	—	2/fMCK + 220	
			1.6 V ≤ VDD ≤ 3.6 V	—	—	—	—	—	—	—	—	

Note 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 4. C is the load capacitance of the SOp output lines.

Note 5. The maximum transfer rate when using the SNOOZE mode is 1 Mbps.

Caution Select the normal input buffer for the Slp pin and the normal output mode for the SOp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

Remark 1. p: CSI number (p = 00), m: Unit number (m = 0), n: Channel number (n = 0), g: PIM and POM numbers (g = 5)

Remark 2. fMCK: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00, 01))

Note 1. The value must also be equal to or less than $f_{MCK}/4$.

Note 2. Set the f_{MCK} value to keep the hold time of $SCLr = "L"$ and $SCLr = "H"$.

Caution Select the normal input buffer and the N-ch open drain output (V_{DD} tolerance) mode for the $SDAr$ pin and the normal output mode for the $SCLr$ pin by using port input mode register g (PIMg) and port output mode register h (POMh).

(8) Communication at different potential (1.8 V, 2.5 V) (CSI mode) (master mode, SCKp... internal clock output)

(TA = +85 to 105°C, 2.4 V ≤ AVDD = VDD ≤ 3.6 V, VSS = AVSS = 0 V)

(1/2)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
SCKp cycle time	tkCY1	tkCY1 ≥ fCLK/4 2.7 V ≤ VDD ≤ 3.6 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ	1000		ns
		2.4 V ≤ VDD < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V, Cb = 30 pF, Rb = 5.5 kΩ	2300		ns
SCKp high-level width	tkH1	2.7 V ≤ VDD ≤ 3.6 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ	tkCY1/2 - 340		ns
		2.4 V ≤ VDD < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V, Cb = 30 pF, Rb = 5.5 kΩ	tkCY1/2 - 916		ns
SCKp low-level width	tkL1	2.7 V ≤ VDD ≤ 3.6 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ	tkCY1/2 - 36		ns
		2.4 V ≤ VDD < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V, Cb = 30 pF, Rb = 5.5 kΩ	tkCY1/2 - 100		ns

Caution Select the TTL input buffer for the SIp pin and the N-ch open drain output (VDD tolerance) mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For VIH and VIL, see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the page after the next page.)

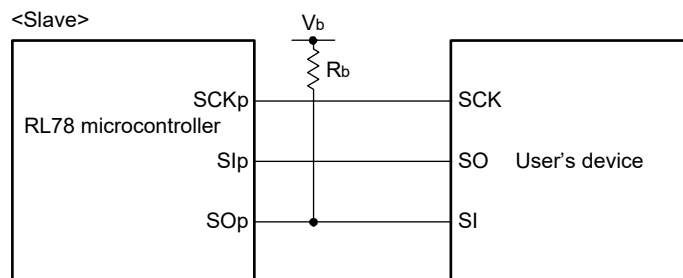
(8) Communication at different potential (1.8 V, 2.5 V) (CSI mode) (master mode, SCKp... internal clock output)**(TA = +85 to 105°C, 2.4 V ≤ AVDD = VDD ≤ 3.6 V, VSS = AVSS = 0 V)****(2/2)**

Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
Slp setup time (to SCKp↑) Note 1	tSIK1	2.7 V ≤ VDD ≤ 3.6 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ	354		ns
		2.4 V ≤ VDD < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V Note 3, Cb = 30 pF, Rb = 5.5 kΩ	958		ns
Slp hold time (from SCKp↑) Note 1	tKSI1	2.7 V ≤ VDD ≤ 3.6 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ	38		ns
		2.4 V ≤ VDD < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V Note 3, Cb = 30 pF, Rb = 5.5 kΩ	38		ns
Delay time from SCKp↓ to SOp output Note 1	tKS01	2.7 V ≤ VDD ≤ 3.6 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ		390	ns
		2.4 V ≤ VDD < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V Note 3, Cb = 30 pF, Rb = 5.5 kΩ		966	ns
Slp setup time (to SCKp↓) Note 2	tSIK1	2.7 V ≤ VDD ≤ 3.6 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ	88		ns
		2.4 V ≤ VDD < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V Note 3, Cb = 30 pF, Rb = 5.5 kΩ	220		ns
Slp hold time (from SCKp↓) Note 2	tKSI1	2.7 V ≤ VDD ≤ 3.6 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ	38		ns
		2.4 V ≤ VDD < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V Note 3, Cb = 30 pF, Rb = 5.5 kΩ	38		ns
Delay time from SCKp↑ to SOp output Note 2	tKS01	2.7 V ≤ VDD ≤ 3.6 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ		50	ns
		2.4 V ≤ VDD < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V Note 3, Cb = 30 pF, Rb = 5.5 kΩ		50	ns

Note 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.**Note 2.** When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.**Note 3.** Use it with VDD ≥ Vb.

Caution Select the TTL input buffer for the Slp pin and the N-ch open drain output (VDD tolerance) mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For VIH and VIL, see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the next page.)

CSI mode connection diagram (during communication at different potential)

Remark 1. $R_b[\Omega]$: Communication line (SO_p) pull-up resistance, $C_b[F]$: Communication line (SO_p) load capacitance, $V_b[V]$: Communication line voltage

Remark 2. p: CSI number (p = 00, 01), m: Unit number (m = 0), n: Channel number (n = 0, 1), g: PIM and POM numbers (g = 5)

Remark 3. f_{MCK} : Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00, 01))

(10) Communication at different potential (1.8 V, 2.5 V) (simplified I²C mode)**(T_A = -40 to 85°C, 1.8 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V)**

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LP (Low-power main) mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCLr clock frequency	f _{SCL}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ		1000 Note 1		300 Note 1		250 Note 1		300 Note 1	kHz
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ		400 Note 1		300 Note 1		250 Note 1		300 Note 1	kHz
		1.8 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ		300 Note 1		300 Note 1		250 Note 1		300 Note 1	kHz
Hold time when SCLr = "L"	t _{LOW}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	475		1550		1550		1550		ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	1150		1550		1550		1550		ns
		1.8 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	1550		1550		1550		1550		ns
Hold time when SCLr = "H"	t _{HIGH}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	200		610		610		610		ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	600		610		610		610		ns
		1.8 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	610		610		610		610		ns
Data setup time (reception)	t _{SDU} : DAT	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	1/f _{MCK} + 135 Note 3		1/f _{MCK} + 190 Note 2		1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		ns
		1.8 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		ns
Data hold time (transmission)	t _{HD} : DAT	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	0	305	0	305	0	305	0	305	ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	0	355	0	355	0	355	0	355	ns
		1.8 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	0	405	0	405	0	405	0	405	ns

Note 1. The value must also be equal to or less than f_{MCK}/4.**Note 2.** Use it with V_{DD} ≥ V_b.**Note 3.** Set the f_{MCK} value to keep the hold time of SCLr = "L" and SCLr = "H".

Caution Select the TTL input buffer and the N-ch open drain output (V_{DD} tolerance) mode for the SDAr pin and the N-ch open drain output (V_{DD} tolerance) mode for the SCLr pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the next page.)

(10) Communication at different potential (1.8 V, 2.5 V) (simplified I²C mode)**(T_A = +85 to 105°C, 2.4 V ≤ AV_{DD} = V_{DD} ≤ 3.6 V, V_{SS} = AV_{SS} = 0 V)**

Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
SCLr clock frequency	f _{SCL}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ		400 Note 1	kHz
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ		100 Note 1	kHz
		2.4 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ		100 Note 1	kHz
Hold time when SCLr = "L"	t _{LOW}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	1200		ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	4600		ns
		2.4 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	4650		ns
Hold time when SCLr = "H"	t _{HIGH}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	500		ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	2400		ns
		2.4 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	1830		ns
Data setup time (reception)	t _{SU-DAT}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	1/f _{MCK} + 340 Note 3		ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	1/f _{MCK} + 760 Note 3		ns
		2.4 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	1/f _{MCK} + 570 Note 3		ns
Data hold time (transmission)	t _{HD-DAT}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	0	770	ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	0	1420	ns
		2.4 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	0	1215	ns

Note 1. The value must also be equal to or less than f_{MCK}/4.**Note 2.** Use it with V_{DD} ≥ V_b.**Note 3.** Set the f_{MCK} value to keep the hold time of SCLr = "L" and SCLr = "H".

Caution Select the TTL input buffer and the N-ch open drain output (V_{DD} tolerance) mode for the SDAr pin and the N-ch open drain output (V_{DD} tolerance) mode for the SCLr pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the next page.)

(1) When reference voltage (+) = $AV_{REFP}/ANI0$ ($ADREFP1 = 0$, $ADREFP0 = 1$), reference voltage (-) = $AV_{REFM}/ANI1$ ($ADREFM = 1$), conversion target: $ANI2$ to $ANI13$

($T_A = -40$ to $+85^{\circ}\text{C}$, $1.6\text{ V} \leq AV_{REFP} \leq AV_{DD} = V_{DD} \leq 3.6\text{ V}$, $V_{SS} = 0\text{ V}$, $AV_{SS} = 0\text{ V}$, Reference voltage (+) = AV_{REFP} , Reference voltage (-) = $AV_{REFM} = 0\text{ V}$)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES		$2.4\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$	8		12	bit
			$1.8\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$	8		10 Note 1	
			$1.6\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$	8 Note 2			
Overall error Note 3	AINL	12-bit resolution	$2.4\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±6.0	LSB
		10-bit resolution	$1.8\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±5.0	
		8-bit resolution	$1.6\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±2.5	
Conversion time	tCONV	ADTYP = 0, 12-bit resolution	$2.4\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$	3.375			μs
		ADTYP = 0, 10-bit resolution Note 1	$1.8\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$	6.75			
		ADTYP = 0, 8-bit resolution Note 2	$1.6\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$	13.5			
		ADTYP = 1, 8-bit resolution	$2.4\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$	2.5625			
			$1.8\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$	5.125			
			$1.6\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$	10.25			
Zero-scale error Note 3	Ezs	12-bit resolution	$2.4\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±4.5	LSB
		10-bit resolution	$1.8\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±4.5	
		8-bit resolution	$1.6\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±2.0	
Full-scale error Note 3	Efs	12-bit resolution	$2.4\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±4.5	LSB
		10-bit resolution	$1.8\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±4.5	
		8-bit resolution	$1.6\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±2.0	
Integral linearity error Note 3	ILE	12-bit resolution	$2.4\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±2.0	LSB
		10-bit resolution	$1.8\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±1.5	
		8-bit resolution	$1.6\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±1.0	
Differential linearity error Note 3	DLE	12-bit resolution	$2.4\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±1.5	LSB
		10-bit resolution	$1.8\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±1.5	
		8-bit resolution	$1.6\text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{AV}_{\text{DD}} \leq 3.6\text{ V}$			±1.0	
Analog input voltage	VAIN			0		AVREFP	V

Note 1. Cannot be used for lower 2 bit of ADCR register

Note 2. Cannot be used for lower 4 bit of ADCR register

Note 3. Excludes quantization error ($\pm 1/2$ LSB).

Caution Always use AV_{DD} pin with the same potential as the V_{DD} pin.

- (3) When reference voltage (+) = $AV_{REFP}/ANI0$ ($ADREFP1 = 0$, $ADREFP0 = 1$), reference voltage (-) = $AV_{REFM}/ANI1$ ($ADREFM = 1$), conversion target: $ANI16$ to $ANI18$, internal reference voltage, temperature sensor output voltage

($T_A = -40$ to $+85^\circ\text{C}$, $1.6\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $1.6\text{ V} \leq AV_{REFP} \leq AV_{DD} = V_{DD} \leq 3.6\text{ V}$, $V_{SS} = 0\text{ V}$, $AV_{SS} = 0\text{ V}$,

Reference voltage (+) = AV_{REFP} , Reference voltage (-) = $AV_{REFM} = 0\text{ V}$)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES		$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$	8		12	bit
			$1.8\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$	8		10 Note 1	
			$1.6\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$	8 Note 2			
Overall error Note 3	AINL	12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±7.0	LSB
		10-bit resolution	$1.8\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±5.5	
		8-bit resolution	$1.6\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±3.0	
Conversion time	tCONV	ADTYP = 0, 12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$	4.125			μs
		ADTYP = 0, 10-bit resolution Note 1	$1.8\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$	9.5			
		ADTYP = 0, 8-bit resolution Note 2	$1.6\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$	57.5			
		ADTYP = 1, 8-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$	3.3125			
			$1.8\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$	7.875			
			$1.6\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$	54.25			
Zero-scale error Note 3	Ezs	12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±5.0	LSB
		10-bit resolution	$1.8\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±5.0	
		8-bit resolution	$1.6\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±2.5	
Full-scale error Note 3	Efs	12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±5.0	LSB
		10-bit resolution	$1.8\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±5.0	
		8-bit resolution	$1.6\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±2.5	
Integral linearity error Note 3	ILE	12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±3.0	LSB
		10-bit resolution	$1.8\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±2.0	
		8-bit resolution	$1.6\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±1.5	
Differential linearity error Note 3	DLE	12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±2.0	LSB
		10-bit resolution	$1.8\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±2.0	
		8-bit resolution	$1.6\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±1.5	
Analog input voltage	VAIN			0		AVREFP	V
		Internal reference voltage ($1.8\text{ V} \leq V_{DD} \leq 3.6\text{ V}$)		VBGR Note 4			
		Temperature sensor output voltage ($1.8\text{ V} \leq V_{DD} \leq 3.6\text{ V}$)		VTMP25 Note 4			

Note 1. Cannot be used for lower 2 bits of ADCR register

Note 2. Cannot be used for lower 4 bits of ADCR register

Note 3. Excludes quantization error ($\pm 1/2$ LSB).

Note 4. Refer to 2.6.2 Temperature sensor, internal reference voltage output characteristics.

Caution Always use AV_{DD} pin with the same potential as the V_{DD} pin.

- (5) When reference voltage (+) = Internal reference voltage (1.45 V) (ADREFP1 = 1, ADREFP0 = 0), reference voltage (-) = AVss (ADREFM = 0), conversion target: ANI0 to ANI13, ANI16 to ANI18

(TA = -40 to +85°C, 1.8 V ≤ AVDD = VDD ≤ 3.6 V, Vss = 0 V, AVss = 0 V, Reference voltage (+) = internal reference voltage, Reference voltage (-) = AVss = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution	RES		8			bit
Conversion time	tCONV	8-bit resolution	16			μs
Zero-scale error Note	Ezs	8-bit resolution			±4.0	LSB
Integral linearity error Note	ILE	8-bit resolution			±2.0	LSB
Differential linearity error Note	DLE	8-bit resolution			±2.5	LSB
Analog input voltage	VAIN		0		VBGR	V

Note Excludes quantization error (±1/2 LSB).

Caution Always use AVDD pin with the same potential as the VDD pin.

- (6) When reference voltage (+) = AVREFP/ANI0 (ADREFP1 = 0, ADREFP0 = 1), reference voltage (-) = AVREFM/ANI1 (ADREFM = 1), conversion target: ANI2 to ANI13

(TA = +85 to +105°C, 2.4 V ≤ AVREFP ≤ AVDD = VDD ≤ 3.6 V, Vss = 0 V, AVss = 0 V, Reference voltage (+) = AVREFP, Reference voltage (-) = AVREFM = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES		2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	8		12	bit
Overall error Note	AINL	12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			±6.0	LSB
Conversion time	tCONV	ADTYP = 0, 12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	3.375			μs
Zero-scale error Note	Ezs	12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			±4.5	LSB
Full-scale error Note	EFS	12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			±4.5	LSB
Integral linearity error Note	ILE	12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			±2.0	LSB
Differential linearity error Note	DLE	12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			±1.5	LSB
Analog input voltage	VAIN			0		AVREFP	V

Note Excludes quantization error (±1/2 LSB).

Caution Always use AVDD pin with the same potential as the VDD pin.

(7) When reference voltage (+) = AVDD (ADREFP1 = 0, ADREFP0 = 0), reference voltage (-) = AVSS (ADREFM = 0), conversion target: ANI0 to ANI13

(TA = +85 to +105°C, 2.4 V ≤ AVDD = VDD ≤ 3.6 V, VSS = 0 V, AVSS = 0 V, Reference voltage (+) = AVDD, Reference voltage (-) = AVSS = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES		2.4 V ≤ AVDD ≤ 3.6 V	8		12	bit
Overall error ^{Note}	AINL	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±7.5	LSB
Conversion time	tCONV	ADTYP = 0, 12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V	3.375			μs
Zero-scale error ^{Note}	Ezs	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±6.0	LSB
Full-scale error ^{Note}	EFS	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±6.0	LSB
Integral linearity error ^{Note}	ILE	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±3.0	LSB
Differential linearity error ^{Note}	DLE	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±2.0	LSB
Analog input voltage	VAIN			0		AVDD	V

Note Excludes quantization error (±1/2 LSB).

Caution Always use AVDD pin with the same potential as the VDD pin.

- (8) When reference voltage (+) = $AV_{REFP}/ANI0$ ($ADREFP1 = 0$, $ADREFP0 = 1$), reference voltage (-) = $AV_{REFM}/ANI1$ ($ADREFM = 1$), conversion target $ANI16$ to $ANI18$, internal reference voltage, temperature sensor output voltage

($T_A = +85$ to $+105^{\circ}\text{C}$, $2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} = V_{DD} \leq 3.6\text{ V}$, $V_{SS} = 0\text{ V}$, $AV_{SS} = 0\text{ V}$, Reference voltage (+) = AV_{REFP} , Reference voltage (-) = $AV_{REFM} = 0\text{ V}$)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES		$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$	8		12	bit
Overall error ^{Note 1}	AINL	12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±7.0	LSB
Conversion time	tCONV	ADTYP = 0, 12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$	4.125			μs
Zero-scale error ^{Note 1}	Ezs	12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±5.0	LSB
Full-scale error ^{Note 1}	EFS	12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±5.0	LSB
Integral linearity error ^{Note 1}	ILE	12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±3.0	LSB
Differential linearity error ^{Note 1}	DLE	12-bit resolution	$2.4\text{ V} \leq AV_{REFP} \leq AV_{DD} \leq 3.6\text{ V}$			±2.0	LSB
Analog input voltage	VAIN			0		AVREFP	V
		Internal reference voltage ($2.4\text{ V} \leq V_{DD} \leq 3.6\text{ V}$)		VBGR ^{Note 2}			
		Temperature sensor output voltage ($2.4\text{ V} \leq V_{DD} \leq 3.6\text{ V}$)		VTMP25 ^{Note 2}			

Note 1. Excludes quantization error ($\pm 1/2$ LSB).

Note 2. Refer to **2.6.2 Temperature sensor, internal reference voltage output characteristics**.

Caution Always use AV_{DD} pin with the same potential as the V_{DD} pin.

(2) LVD Detection Voltage of Interrupt & Reset Mode

(TA = -40 to +85°C, VPDR ≤ AVDD = VDD ≤ 3.6 V, VSS = AVSS = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit	
Interrupt and reset mode	VLVDA0	VPOC0, VPOC1, VPOC2 = 0, 0, 0, falling reset voltage			1.60	1.63	1.66	V
	VLVDA1	LVIS0, LVIS1 = 1, 0	Rising release reset voltage	1.74	1.77	1.81	V	
			Falling interrupt voltage	1.70	1.73	1.77	V	
	VLVDA2	LVIS0, LVIS1 = 0, 1	Rising release reset voltage	1.84	1.88	1.91	V	
			Falling interrupt voltage	1.80	1.84	1.87	V	
	VLVDA3	LVIS0, LVIS1 = 0, 0	Rising release reset voltage	2.86	2.92	2.97	V	
			Falling interrupt voltage	2.80	2.86	2.91	V	
	VLVDB0	VPOC0, VPOC1, VPOC2 = 0, 0, 1, falling reset voltage			1.80	1.84	1.87	V
	VLVDB1	LVIS0, LVIS1 = 1, 0	Rising release reset voltage	1.94	1.98	2.02	V	
			Falling interrupt voltage	1.90	1.94	1.98	V	
	VLVDB2	LVIS0, LVIS1 = 0, 1	Rising release reset voltage	2.05	2.09	2.13	V	
			Falling interrupt voltage	2.00	2.04	2.08	V	
	VLVDB3	LVIS0, LVIS1 = 0, 0	Rising release reset voltage	3.07	3.13	3.19	V	
			Falling interrupt voltage	3.00	3.06	3.12	V	
	VLVDC0	VPOC0, VPOC1, VPOC2 = 0, 1, 0, falling reset voltage			2.40	2.45	2.50	V
	VLVDC1	LVIS0, LVIS1 = 1, 0	Rising release reset voltage	2.56	2.61	2.66	V	
			Falling interrupt voltage	2.50	2.55	2.60	V	
	VLVDC2	LVIS0, LVIS1 = 0, 1	Rising release reset voltage	2.66	2.71	2.76	V	
			Falling interrupt voltage	2.60	2.65	2.70	V	
	VLVDD0	VPOC0, VPOC1, VPOC2 = 0, 1, 1, falling reset voltage			2.70	2.75	2.81	V
	VLVDD1	LVIS0, LVIS1 = 1, 0	Rising release reset voltage	2.86	2.92	2.97	V	
			Falling interrupt voltage	2.80	2.86	2.91	V	
	VLVDD2	LVIS0, LVIS1 = 0, 1	Rising release reset voltage	2.96	3.02	3.08	V	
			Falling interrupt voltage	2.90	2.96	3.02	V	

(TA = +85 to +105°C, VPDR ≤ AVDD = VDD ≤ 3.6 V, VSS = AVSS = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Interrupt and reset mode	VLVDD0	VPOC0, VPOC1, VPOC2 = 0, 1, 1, falling reset voltage		2.64	2.75	2.86	V
	VLVDD1	LVIS0, LVIS1 = 1, 0	Rising release reset voltage	2.81	2.92	3.03	V
			Falling interrupt voltage	2.75	2.86	2.97	V
	VLVDD2	LVIS0, LVIS1 = 0, 1	Rising release reset voltage	2.90	3.02	3.14	V
			Falling interrupt voltage	2.85	2.96	3.07	V

2.6.7 Power supply voltage rising slope characteristics

(TA = -40 to +105°C, VSS = AVSS = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power supply voltage rising slope	SVDD				54	V/ms

Caution Make sure to keep the internal reset state by the LVD circuit or an external reset until VDD reaches the operating voltage range shown in 2.4 AC Characteristics.